

NOTES :

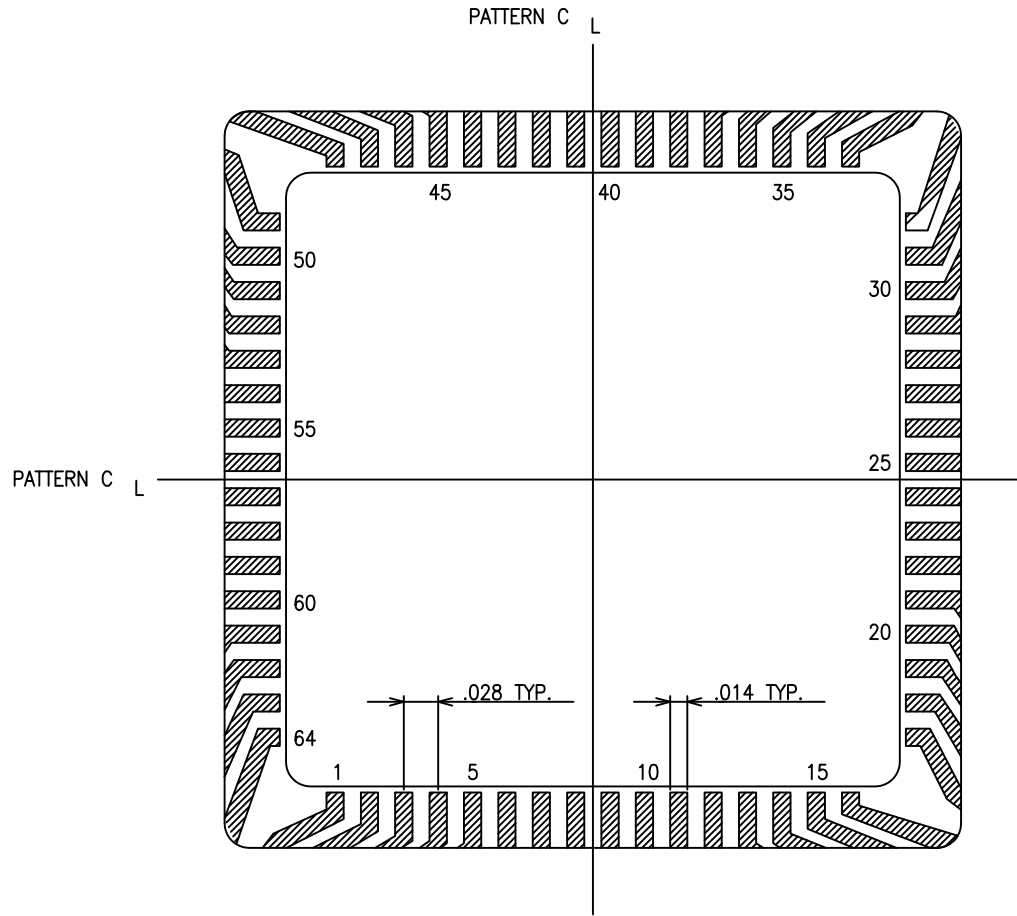
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.50 OHM MAX.

MODIFICATION						
△	REDRAWN (CONVERTED CAD DATA)	DEC.16.'93	K.IM	H.S/K.M	T.A	
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	

NAME	65 PIN GRID ARRAY PACKAGE	TOLERANCE	±.005
SCALE	4 / 1	UNLESS OTHERWISE SPECIFIED	THIRD ANGLE PROJECTION
MATERIAL	AS INDICATED		
		KYOCERA CORPORATION KYOTO JAPAN	

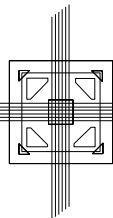
PB065N703-1				S=0
				N=0
DRAWN	CHECKED	APPROVED	DATE	
M.K	K.M		NOV.28.'83	
DRAWING NO.				SHEET
KD-P83703-C				1 / 3





BONDING PATTERN

MODIFICATION						NAME 65 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN M.K	CHECKED K.M	APPROVED	DATE NOV.28.'83
						SCALE 10 / 1	MATERIAL				
	△	REDRAWN (CONVERTED CAD DATA) CHANGED	DEC.16.'93	K.IM	H.S/K.M	T.A					
		DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-P83703-C		SHEET 2/3	



# SSM P/N CPG06402

## WIRE BOND PAD / CONNECTOR

## PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.
1	A1	21	D9	41	K5	61	C1
2	B3	22	D10	42	J5	62	C2
3	A2	23	E10	43	K4	63	B1
4	A3	24	E9	44	J4	64	B2
5	B4	25	F10	45	K3		
6	A4	26	F9	46	J3		
7	A5	27	G10	47	K2		
8	B5	28	G9	48	J2		
9	A6	29	H10	49	K1		
10	B6	30	H9	50	H2		
11	A7	31	J10	51	J1		
12	B7	32	J9	52	H1		
13	A8	33	K10	53	G2		
14	B8	34	J8	54	G1		
15	A9	35	K9	55	F1		
16	B9	36	K8	56	F2		
17	A10	37	J7	57	E1		
18	C9	38	K7	58	E2		
19	B10	39	K6	59	D1		
20	C10	40	J6	60	D2		

S/R	NC
D/A	NC
EXTRA PIN (H3)	H2

MODIFICATION						NAME 65 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN M.K	CHECKED K.M	APPROVED	DATE NOV.28.'83
						SCALE X	MATERIAL				
	△	REDRAWN (CONVERTED CAD DATA) CHANGED	DEC.16.'93	K.IM	H.S./K.M	T.A		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-P83703-C		SHEET 3/3



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